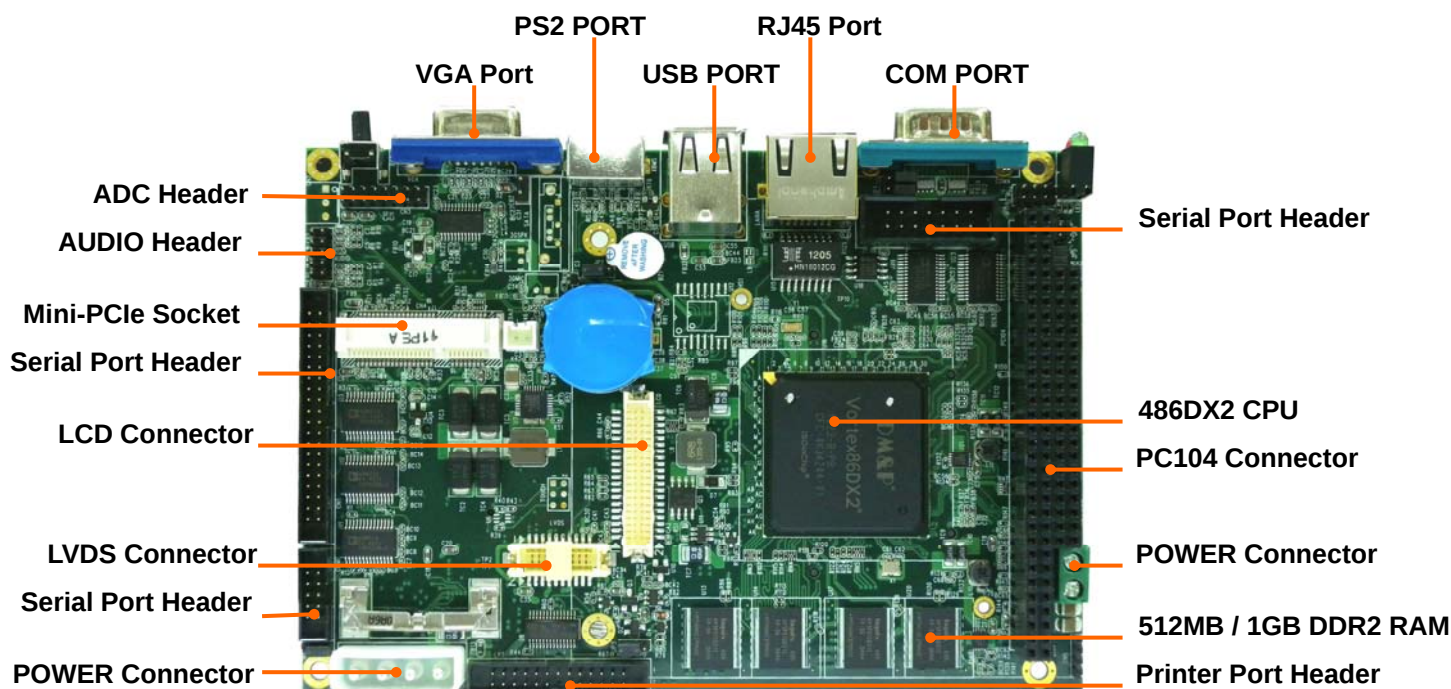




Specifications

- CPU: 800MHz 486DX2 CPU (1.2GHz in future)
- DRAM on board: 512MB DDR-II SDRAM (max 1GB)
- CRT VGA: DB15 on bracket
- LCD interface: TTL TFT LCD, optional LVDS
- 100/10M Ethernet x 1: RJ45 Connector on bracket
- Bus type: PC/104 Socket
- Mini-PCle socket x 1 : Full-size mini-PCle socket x 1; Optional support 3G/WCDMA/HSDPA with SIM socket
- **Optional Mini-PCle socket x 2**
- Audio: HD Audio
- SPI Flash : Optional PI Flash 2/4/8/16MB on board
- **USB2.0 Host x 4: 2 port bracket, 1 port on mini-PCle, 1 port Pin header**
- CFast socket for SATA Flash Disk Module or optional SATA HDD connector
- CMOS Backup: 2pin JSP or Li battery on board
- 8-bit GPIO/DIO: optional max. 56-bit GPIO (DIO)
- COM x 4 (optional COM x 6): RS-232 x 3 + Jumper selectable RS-232/422/485 x 1 + optional RS-232/GPIOx2
- Optional 4/5/6-wire Resistive Touch Controller
- Parallel LPT Port : Bi-directional SPP/EPP/ECP port; Optional GPIO (DIO)
- WDT
- ADC: 8CH
- PS/2 Keyboard & Mouse: mini DIM on bracket
- Power Requirement: Single +5V power DC-IN, Optional 8V ~28V DC-IN
- Dimension: 146mm x 102mm 3.5" form factor
- Operating Temperature: 0 to 60°C; **Optional** -40 to +85°C Wide Temperature

Features

486DX2-800MHz CPU, 512MB soldered RAM, TTL TFT LCD, CRT, LAN x 1, PC/104 socket, mini-PCle x 1, Audio, SPI Flash, USB2.0 x 4, CFast/SATA, RS-232x3 + RS-232/422/485x1, LPT, WDT, KB / Mouse, Single +5V; **Optional:** LVDS, Touch, max. 56-bit DIO, 8V ~28V DCIN, support 3G/WCDMA/HSDPA with SIM socket, COM x 6, mini-PCle x 2

Packing List